

<b>PCN Number:</b>	20190717000.1		<b>PCN Date:</b>	Jul 22, 2019	
<b>Title:</b>	Qualification of additional Fab site (UMC-F12X) and Assembly site (SCK) options for select devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Oct 22, 2019	<b>Estimated Sample Availability:</b>		Date provided at sample request.	
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
Texas Instruments is pleased to announce the qualification of an additional Fab site (UMC-F12X) and Assembly site (SCK) options for the selected devices listed in the "Product Affected" section.					
<b>Current Site</b>			<b>Additional Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>New Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
UMC-F12	C28	300 mm	UMC-F12X	C28	300 mm
No Assembly material differences between sites.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Fab Site Information:</b>					
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City		
UMC-F12	F12	TWN	Tainan		
<b>UMC-F12X</b>	<b>UCX</b>	<b>CHN</b>	<b>Xiamen</b>		
<b>Assembly Site Information:</b>					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly Site City		
Amkor K4	AMP	KOR	Gwangju		
<b>STATS ChipPAC</b>	<b>SCK</b>	<b>KOR</b>	<b>Incheon</b>		

Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 20:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM:  
LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483S12  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACC: MYS

**Product Affected:**

AM5726BABCX	AM5727BABCXEA	AM5729BABCX	AM5729BABCXEAR
AM5726BABCXA	AM5728BABCX	AM5729BABCXA	XAM5728BABCXTUEA
AM5726BABCXAR	AM5728BABCXA	AM5729BABCXEA	XAM5729BABCXTUEA
AM5726BABCXEA	AM5728BABCXEA		

**Qualification Report**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device #1: X5777BXXGABC	Qual Device #2: X5777BXXGABC	Qual Device #3: X5777BXXGABC
HTOL	High Temp Operating Life, 125C	1000 Hours	2/154/0	1/777/0	N/A
ELFR	Early Life Failure Rate, 125C	48 Hours	2/1600/0	1/800/0	N/A
HTSL	High Temp Storage Life, 150C	1000 Hours	2/154/0	1/777/0	3/231/0
CDM	ESD - CDM	250 V	QBS #2	1/3/0	1/3/0
HBM	ESD - HBM	500, 1000, 1500* V	1/3/0	QBS #1	N/A
LU	Latch-up, 125C	+/- 100 mA	1/6/0	QBS #1	N/A
TC	Temperature Cycle, -55/125C	1000 Cycles	2/154/0	1/777/0	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	2/154/0	1/777/0	3/231/0
UHAST	Unbiased HAST 110C/85%RH	264 Hours	2/154/0	1/777/0	3/231/0

- QBS: Qualification By Similarity
- Qualification Device X5777BXXGABC is qualified at LEVEL3-250C
- \* Indicates supplemental data that extends beyond the qualification requirement.
- Preconditioning was performed for Unbiased HAST, THB, Temperature Cycle, and HTSL.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free (SMT) and Green

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